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PRODUCT CHANGE NOTIFICATION

PCN: PCN135246

Date: September 14, 2013

Subject: Qualification of Cypress Minnesota Inc. as an alternative wafer fabrication site and Copper Palladium as an alternative wire bond option for select PSoC Capsense Controller Product families.

To: JAMIE PEDERSON
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Change Type: Major

Description of Change:

Cypress announces the qualification of an alternate wafer fabrication site, Cypress's in-house wafer manufacturing facility, Cypress Minnesota Inc. (CMI), for select PSoC Capsense Controller Product families (CY8C20xx7 & CY8C20055).

This product will run on SONOS8 process technology, which has been previously qualified at CMI to support production quantities. The SONOS8 technology is also qualified at Cypress's subcontractor site Grace Semiconductor Manufacturing Corporation (GSMC).

Effective 90 days from the date of this notification, shipments may be sourced from any qualified manufacturing site, i.e., CMI and GSMC.

Cypress also announces the qualification of Copper Palladium (CuPd) as an alternate wire bond option to Gold (Au) in 16QFN package for select PSoC Capsense Controller Product families.

Effective 90 days from the date of this notification, shipments may be sourced from any qualified assembly site, i.e., Advanced Semiconductor Engineering (ASE) and Cypress Manufacturing Ltd. (CML).

Benefit of Change:

Cypress will have the added capability to meet varying market demand, and to ensure consistent and reliable delivery performance to customers.

Affected Part Numbers:

Affected Parts: 105

See part number list in the attachment.

Customer Part Numbers Affected:

Affected Parts: N/A

Qualification Status:

The alternate wafer fabrication site has been qualified through a series of tests identified in the Qualification Test Plan (QTP) Report #130702. The alternate wire bond option has been qualified through a series of tests identified in QTP Reports #132703 and #132901. The QTP report can be found in the attachment to this notification or by visiting www.cypress.com, typing the QTP number in the search window, and clicking on the magnifying glass icon.

Sample Status:

Qualification samples are not built ahead of time for all part numbers affected by this change. Please review the attached table for a list of affected part numbers with their associated sample ordering part numbers. If you require qualification samples, please contact your sales representative as soon as possible, but within 30 days of the date of this PCN.

Qualification sample orders received after 30 days from the date of this PCN and qualification sample orders for parts which do not have a listed sample ordering part number in the table above will be subject to lead times.

Approximate Implementation Date:

This change will be implemented 90 days from the date of this notification. Effective 90 days from the date of this notification, all shipments of the affected part numbers will be fabricated at either CMI or GSMC and with either CuPd or Au wire bonds.

Anticipated Impact:

Products manufactured are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress also recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:

No response is required.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration